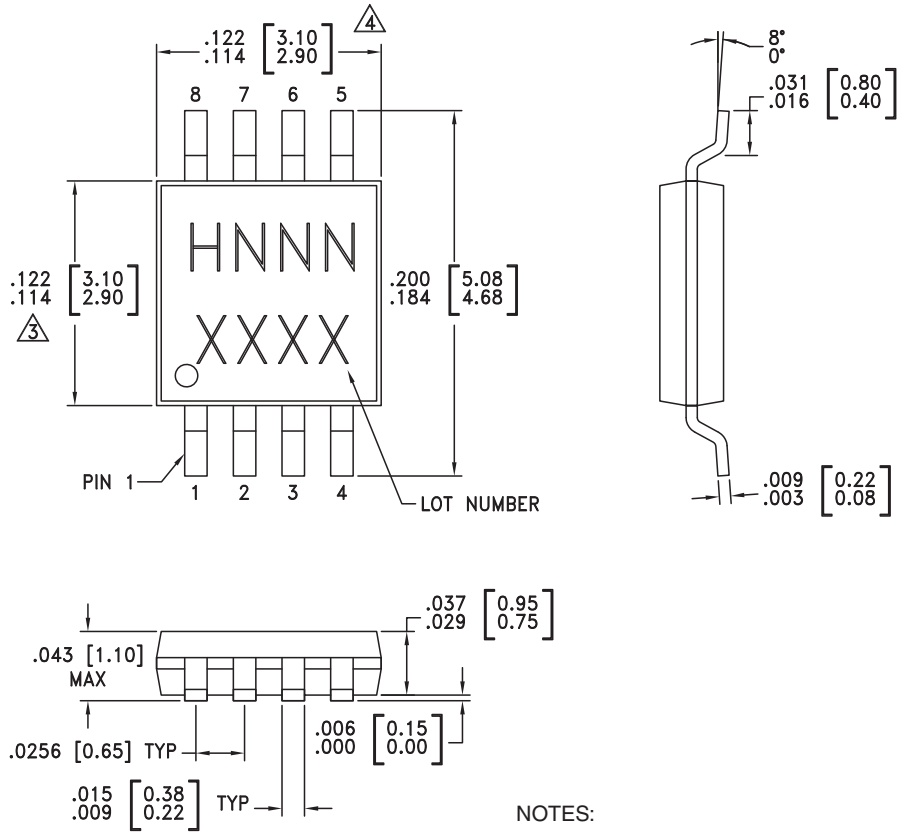


**MS8 (E) – 8 LEAD  
PLASTIC MSOP PACKAGE**

**MS8 (E) Package Outline Drawing**



**NOTES:**

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- △ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

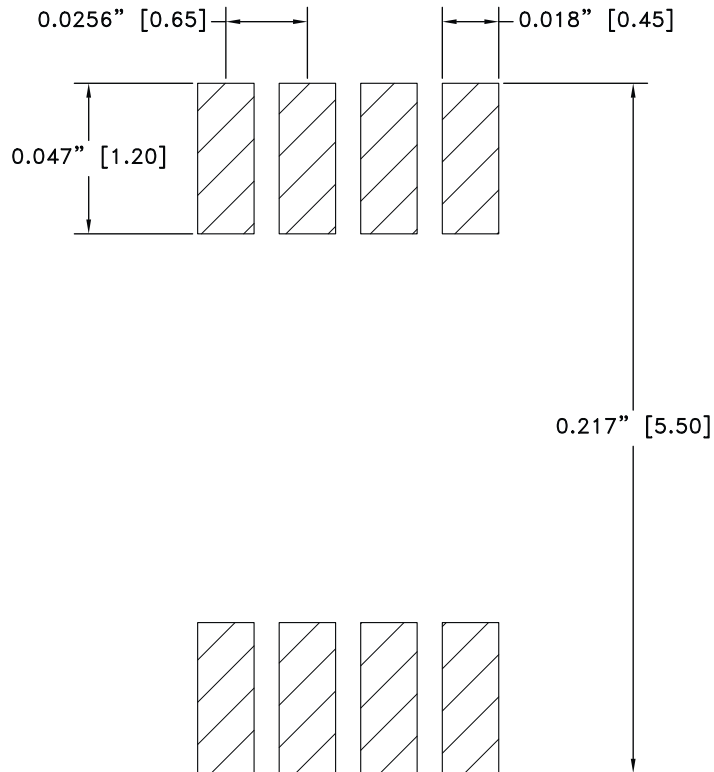
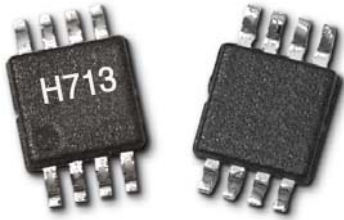
**Package Information**

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking <sup>[3][4]</sup>
MS8	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 <sup>[1]</sup>	HNNN XXXX
MS8E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 <sup>[2]</sup>	HNNN XXXX

[1] Max peak reflow temperature of 235 °C  
 [2] Max peak reflow temperature of 260 °C  
 [3] 4-Digit lot number XXXX  
 [4] 3-Digit part number NNN

**MS8 (E) – 8 LEAD  
 PLASTIC MSOP PACKAGE**

**Suggested MS8 (E) PCB Land Pattern**

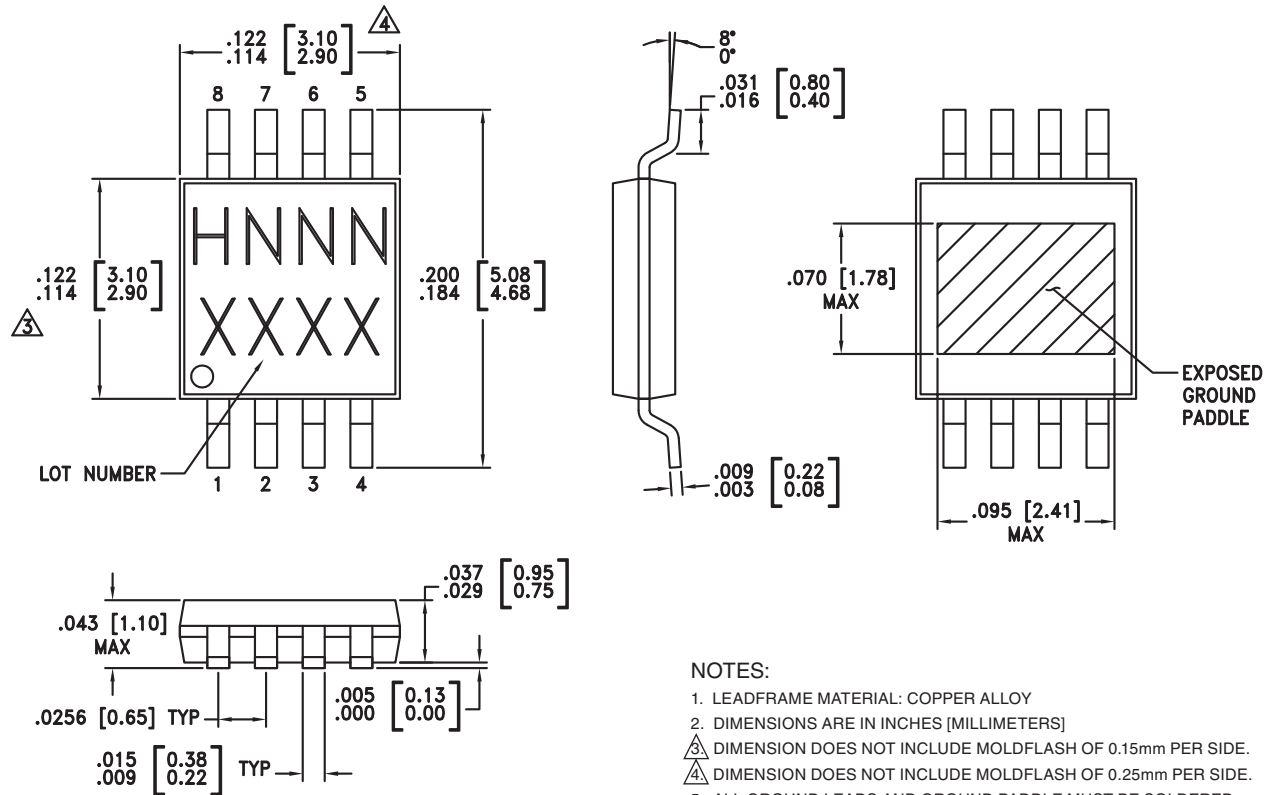


**NOTES:**

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.

## MS8G (E) – 8 LEAD PLASTIC MSOP PACKAGE WITH EXPOSED BASE

MS8G (E) Package Outline Drawing



**NOTES:**

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- ⊠ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- ⊡ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

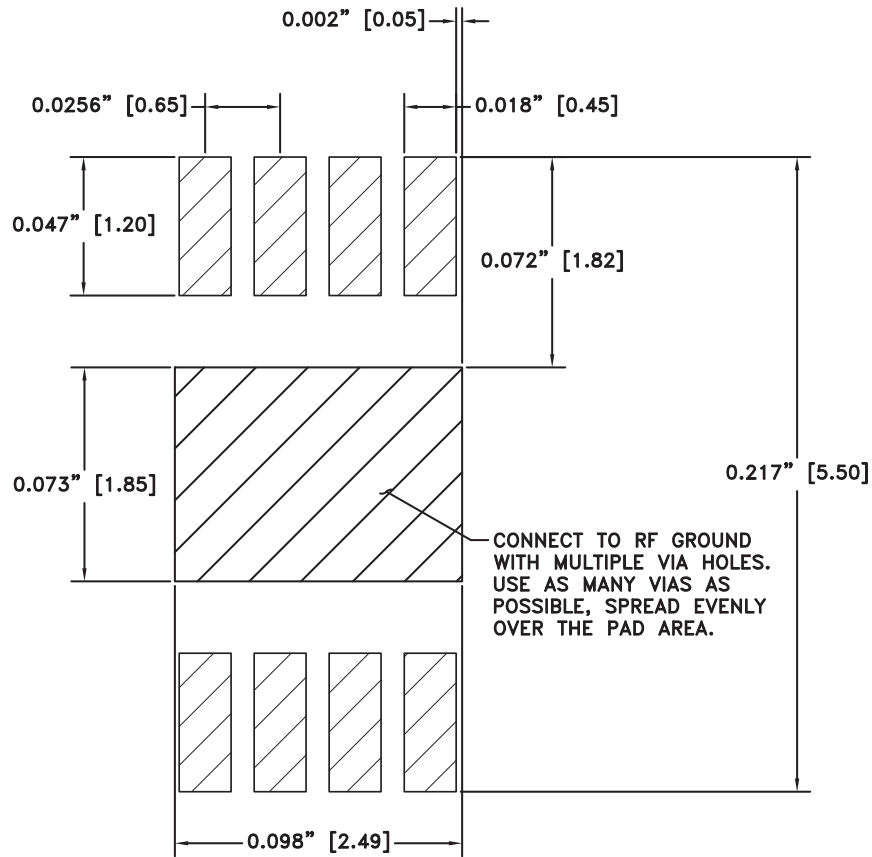
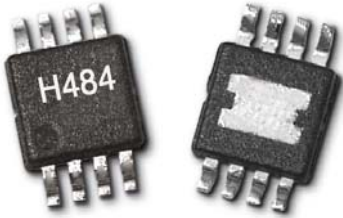
### Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking <sup>[3][4]</sup>
MSG8	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 <sup>[1]</sup>	HNNN XXXX
MS8GE	RoHS Compliant Mold Compound	100% matte Sn	MSL1 <sup>[2]</sup>	HNNN XXXX

[1] Max peak reflow temperature of 235 °C  
 [2] Max peak reflow temperature of 260 °C  
 [3] 4-Digit lot number XXXX  
 [4] 3-Digit part number NNN

**MS8G (E) – 8 LEAD PLASTIC MSOP  
PACKAGE WITH EXPOSED BASE**

**Suggested MS8G (E) PCB Land Pattern**



**NOTES:**

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.

